

Filename: PMP7034 REV_A_bom.xls

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PMP7034 REV_A BOM

COUNT	RefDes	Value	Description	Size	Part Number	MFR
1	C3	0.47uF	Capacitor, Ceramic, 16V, X7R, 15%	0603	Std	Std
1	C9	4700pF	Capacitor, Ceramic, 4700pF, 2KV, X7R, 10%	1812	Std	AVX
1	C10	0.1uF	Capacitor, Ceramic, 25V, X7R, 15%	0603	Std	Std
1	C12	1uF	Capacitor, Ceramic, 16V, X7R, 20%	0603	Std	Std
1	C15	220pF	Capacitor, Ceramic, 50V, NPO, 15%	0603	Std	Std
1	C16	0.047uF	Capacitor, Ceramic, 25V, X7R, 10%	0603	Std	Std
1	C17	47pF	Capacitor, Ceramic, 50V, NPO, 15%	0603	Std	Std
1	C18	470pF	Capacitor, Ceramic, 25V, X7R, 10%	0603	Std	Std
1	C19	3300pF	Capacitor, Ceramic, 25V, X7R, 10%	0603	Std	Std
1	C20	4.7uF	Capacitor, Ceramic, 16V, X7R, 10%	0805	C2012X7R1E475K	TDK
2	C11 C13	470pF	Capacitor, Ceramic, 50V, NPO, 5%	0603	Std	Std
4	C1-2 C100-101	100uF	Capacitor, Ceramic, 6.3V, X5R, 15%	1210	C3225X5R0J107MT	TDK
2	C4 C6	2.2uF	Capacitor, Ceramic, 6.3V, X5R, 15%	0603	std	TDK
2	C5 C14	0.22uF	Capacitor, Ceramic, 16V, X7R, 15%	0603	Std	Std
2	C7-8	47uF	Capacitor, Ceramic, 16V, X5R, 20%	1210	ECJ4YB1C476M	Panasonic
1	D1	MBR0540	Diode, Schottky, 0.5A, 40V	SOD-123	MBR0540T1	ON Semi
1	D2	MBRS360	Diode, Schottky, 3A, 60V	SMC	MBRS360T3	On Semi
2	D3 D100	BAS16	Diode, Switching, 10-mA, 85-V, 350-mW	SOT23	BAS16LT1	On Semi
1	J1	ED1514	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25	ED1514	OST
1	J2	ED1514	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25"	ED1514	OST
1	L1	0.33uH	Inductor, SMT, 10-A, 4-milliohm	0.235 x 0.380	DO1813H-331ML	Coilcraft
1	L2	2.2uH	Inductor, SMT, 3.5-A, 35-milliohm	0.235 x 0.380	DO1813H-222ML	Coilcraft
1	Q1	CSD16340Q3	MOSFET, NChan, 25V, 21A, 3.8 milliOhm	QFN3.3x3.3 mm	CSD16340Q3	Texas Instruments
1	R1	300	Resistor, Metal Film, 1/4 watt, ± 5%	1206	Std	Vishay
1	R2	1	Resistor, Chip, 1/10W, 1%	0805	Std	Std
1	R4	open	Resistor, Chip, 1/16W, 1%	0603	std	std
1	R5	392K	Resistor, Chip, 1/16W, 1%	0603	std	std
1	R6	200	Resistor, Chip, 1/10W, 1%	0805	Std	Std
1	R9	0	Resistor, Chip, 1%, 0603	0603	Std	Std
1	R10	2K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R11	10K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R12	4.7K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R13	76.8K	Resistor, Chip, 1/16W, 1%	0603	Std	Std

1	R14	5-milliOhm	Resistor, Chip, 1/4W, 1%	1210	Std	Std
1	R15	1k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R17	4.99K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R18	11.5K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R20	100K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R21	499	Resistor, Chip, 1/16W, 1%	0603	std	std
1	R22	DNP	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R16 R23	20K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R3 R7	0	Resistor, Chip, 1/16W, 1%	0603	std	std
2	R8 R19	49.9	Resistor, Chip, 1/16W, 1%	0603	std	std
1	T1	2.5uH	Transformer, Flyback	0.708 x 941 inch	See description	Any
8	TP1 TP3 TP5-10	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
2	TP2 TP4	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
1	U1	REG710NA-5	IC, Switched-Cap Buck-Boost Converter, 5V	SOT23-6	REG710NA-5	Texas Instruments
1	U2	TPS40210DGS	IC, Current Mode Boost Controller	DGS10	TPS40210DGS	Texas Instruments
1	U3	TCMT1107	IC, Photocoupler, CTR = 80% - 160%	MF4	TCMT1107	Vishay
1	U4	TL431A	IC, Precision Adjustable Shunt Regulator	SOT23-3	TL431AIDBZ	Texas Instruments

- Notes:
1. These assemblies are ESD sensitive, ESD precautions shall be observed.
 2. These assemblies must be clean and free from flux and all contaminants.
Use of no clean flux is not acceptable.
 3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.
 4. Ref designators marked with an asterisk (***) cannot be substituted.
All other components can be substituted with equivalent MFG's components.

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